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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Appl. No. | 10/813,407 | Confirmation No. | 5642 |
| First Inventor | Jiping Li | Filing Date | March 29, 2004 |
| Tech. Center/ Art Unit | 2822 | Examiner | Trinh, Michael Manh |
| Title: | High Throughput Measurement Of Via Defects In Interconnects | | |
| Docket No.: | 008546USA | Customer No.: | 34036 |

Santa Clara, California
December 20, 2005

Mail Stop ISSUE FEE
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AMENDMENT AFTER NOTICE OF ALLOWANCE

UNDER 37 C.F.R. 1.312

Dear Sir:

In response to Notice of Allowance dated April 27, 2005, please amend the above-identified application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Drawings begin on page 3 of this paper and include two replacement sheets.

Remarks/Arguments begin on page 4 of this paper.

An **Appendix** including two replacement drawing figures (and a cover sheet) is attached following page 4 of this paper.

OK. to
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to Specification
and Drawing
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